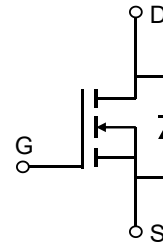


Description

Features

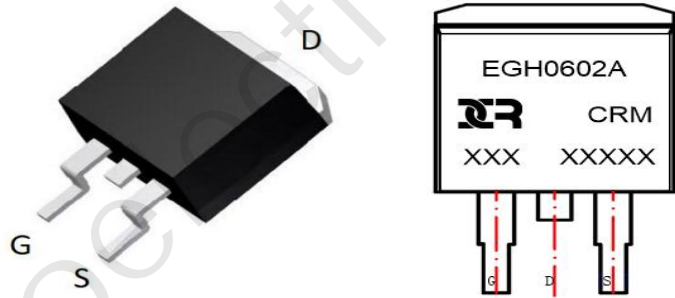
- 60V, 200A
 $R_{DS(ON)}$ Typ = 1.8mΩ @ $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMEGH0602A	CRMEGH0602A	TO-263-3L	TAPING	13"	800	4000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	60	V
V_{GS}	Gate-to-Source Voltage	±20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	200
		$T_C = 100^\circ\text{C}$	120
I_{DM}	Pulsed Drain Current ⁽¹⁾	800	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	784	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	138
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.9	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
--------	-----------	------------	------	------	------	------

Off Characteristics

V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2	3	4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 30A	-	1.8	2.2	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	-	7397	-	pF
C _{oss}	Output Capacitance		-	3885	-	pF
C _{rss}	Reverse Transfer Capacitance		-	203	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 30V, I _D = 30A	-	120	-	nC
Q _{gs}	Gate Source Charge		-	37	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	33	-	nC

Switching Characteristics

t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 30V I _D = 30A, R _{GEN} = 3Ω	-	26	-	ns
t _r	Turn-On Rise Time		-	33	-	ns
t _{d(off)}	Turn-Off DelayTime		-	50	-	ns
t _f	Turn-Off Fall Time		-	25	-	ns

Drain-Source Diode Characteristics and Max Ratings

I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	200	A	
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	800	A	
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V

- Notes:
1. Repetitive RatinCRMGGL0603B
 2. E_{AS} condition: Starting T_J=25°C, V_{DD}=30V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=56A
 3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Performance Characteristics

Figure 1: Output Characteristics

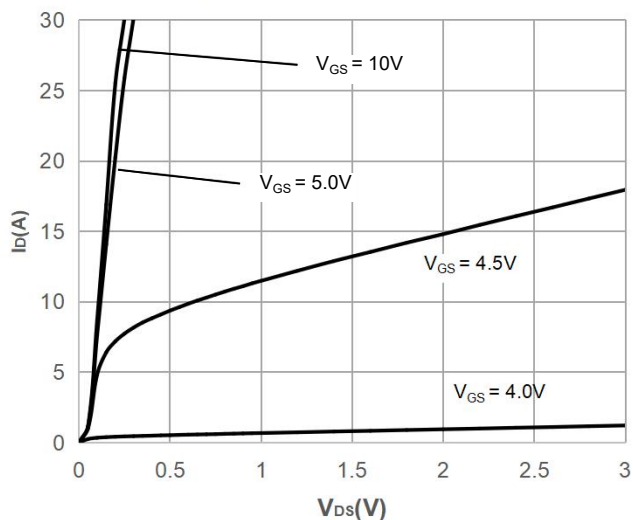


Figure 2: Typical Transfer Characteristics

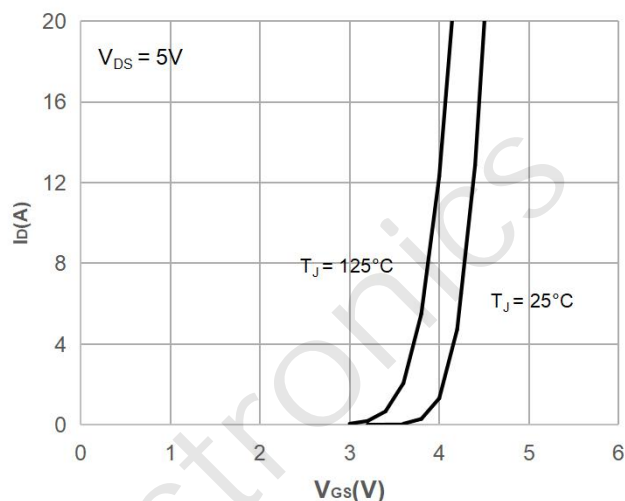


Figure 3: On-resistance vs. Drain Current

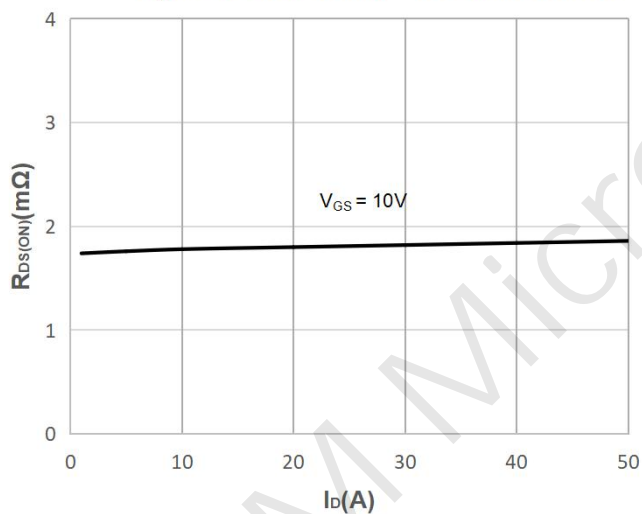


Figure 4: Body Diode Characteristics

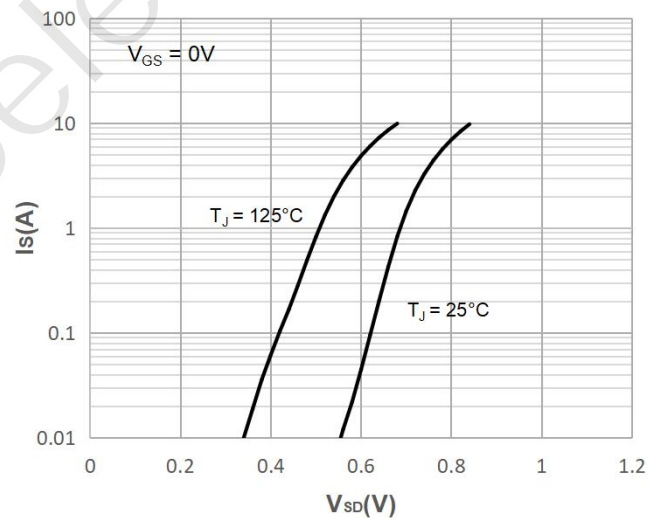


Figure 5: Gate Charge Characteristics

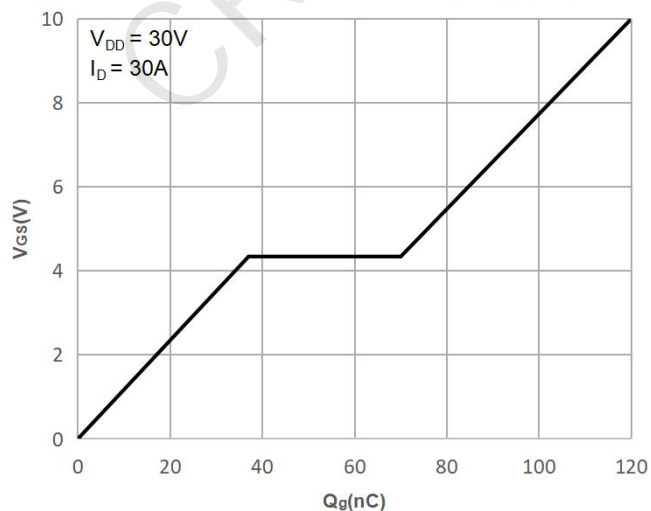
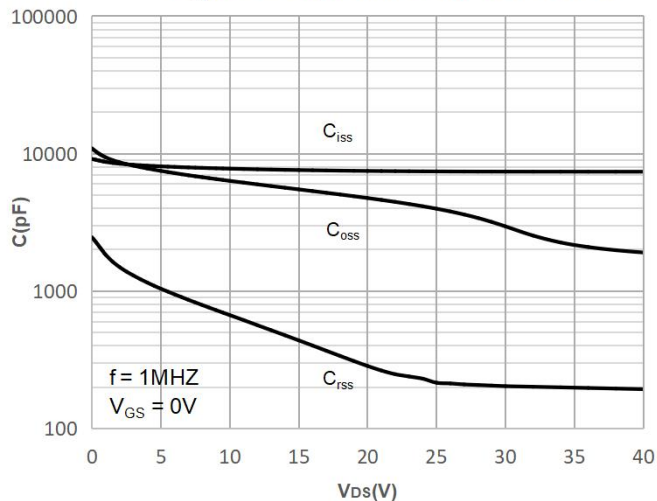


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

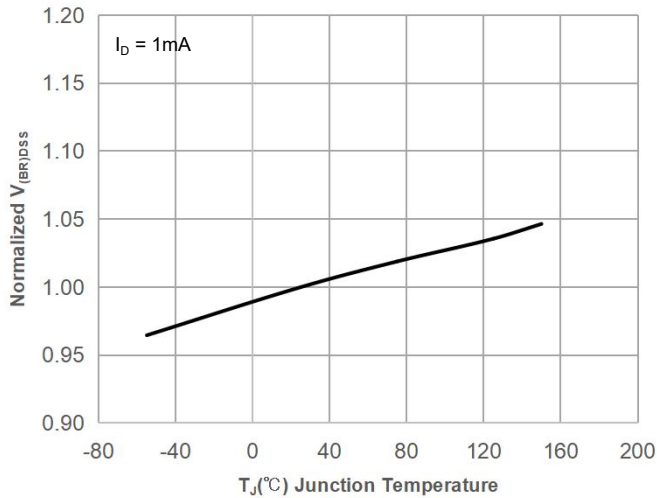


Figure 8: Normalized on Resistance vs. Junction Temperature

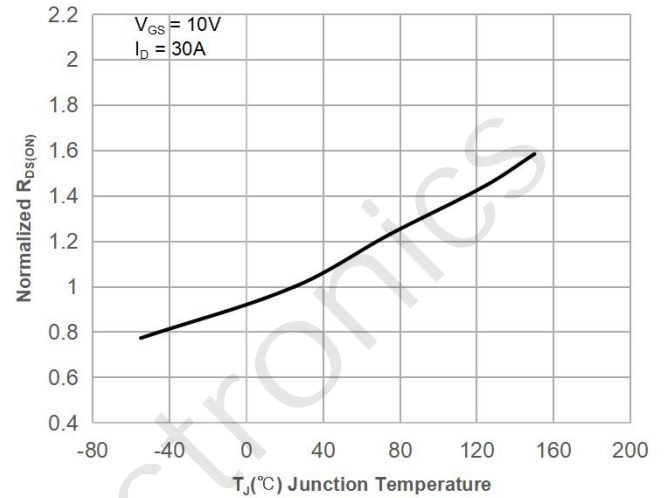


Figure 9: Maximum Safe Operating Area

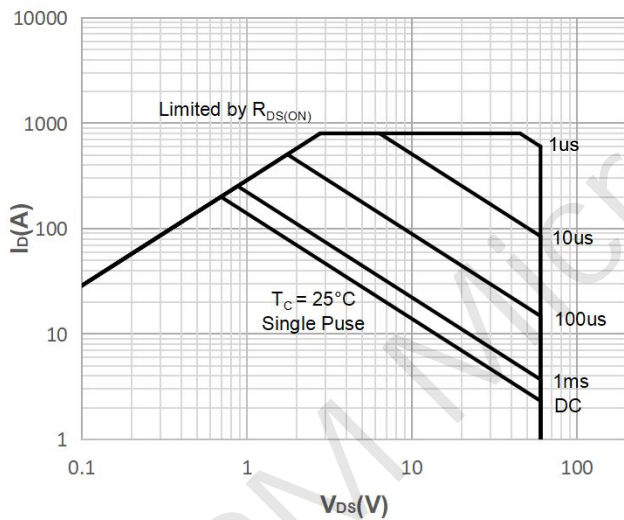


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

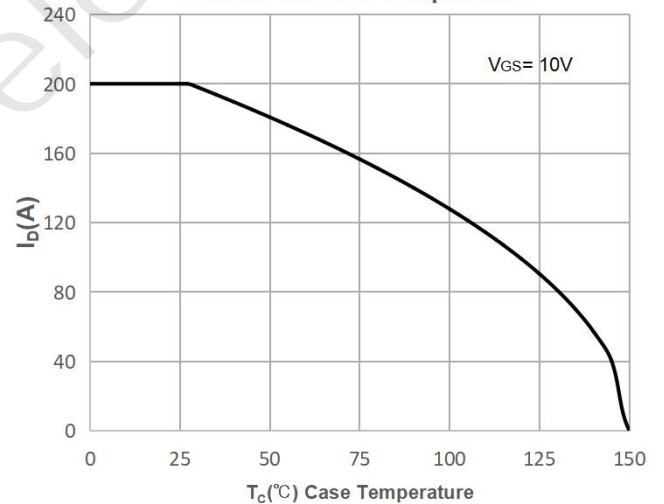


Figure 11: Normalized Maximum Transient Thermal Impedance

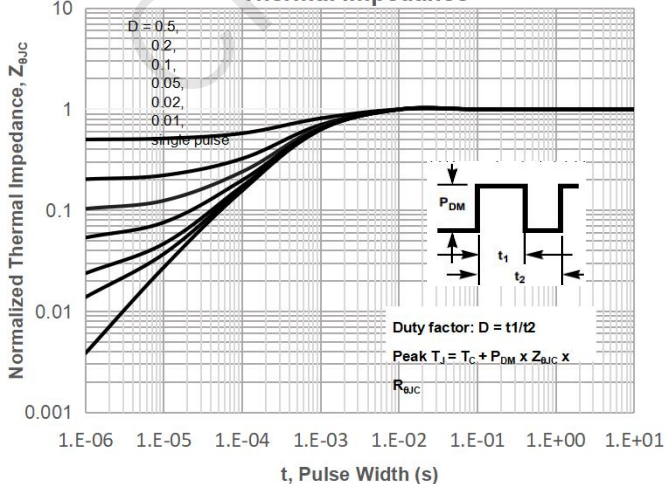
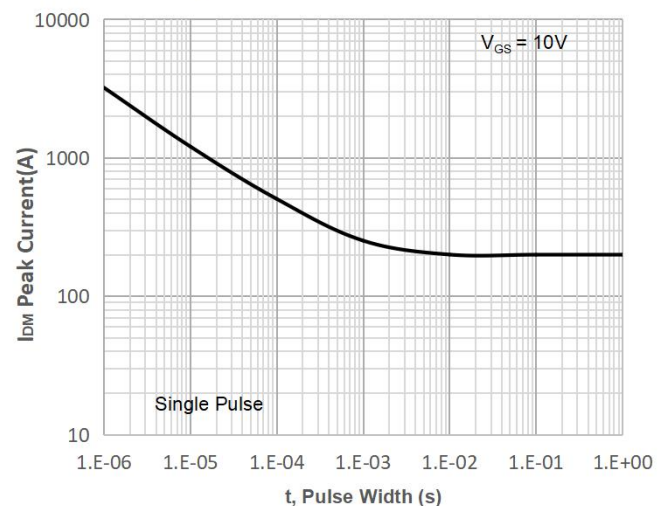


Figure 12: Peak Current Capacity



Test Circuit

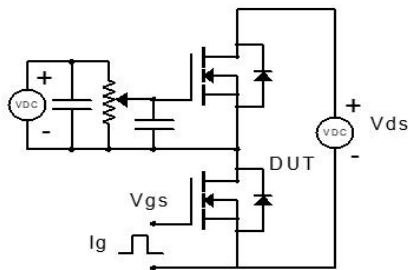


Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform



Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

200

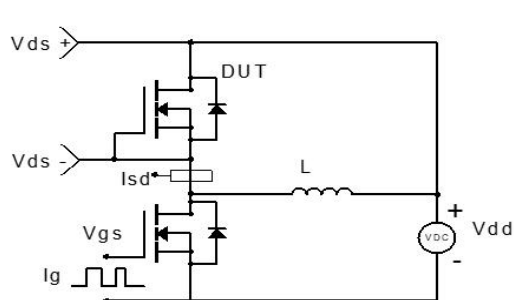
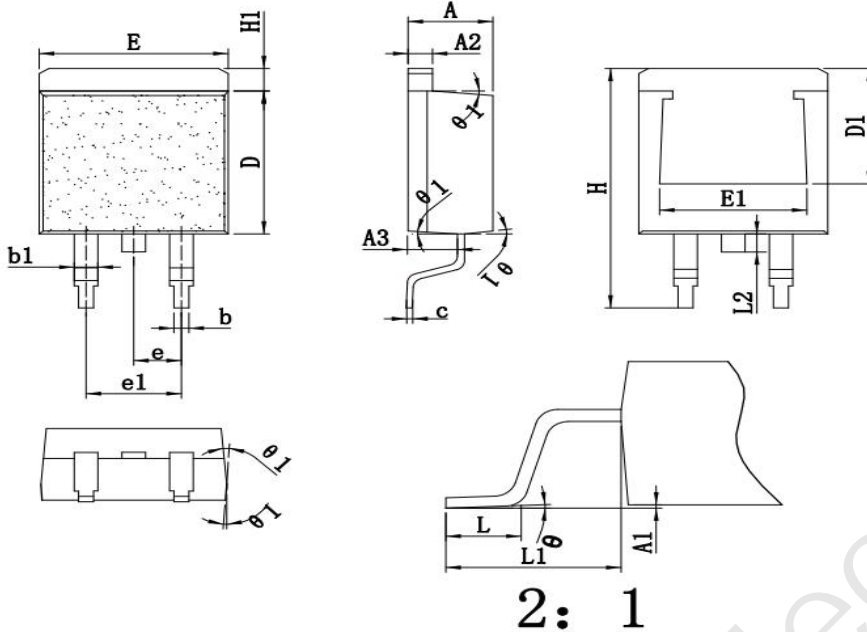


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-263-3L)



SYMBOL	mm		
	MIN	NOM	MAX
*A	4.42	4.52	4.62
*A1	0.00	0.10	0.20
*A2	1.24	1.27	1.32
*A3	2.50	2.60	2.70
*b	0.77	0.81	0.84
*b1	1.23	1.28	1.41
*c	0.33	0.38	0.43
*D	8.80	8.95	9.10
D1	7.25REF		
*E	9.92	10.07	10.22
E1	7.85REF		
*e	2.50	2.54	2.58
e1	5.08REF		
*H	14.80	15.10	15.30
H1	1.12	1.28	1.42
*L	2.10	2.23	2.36
L1	4.55	4.75	4.95
L2	1.10	1.30	1.50
*θ	0°	2°	5°
θ1	3°	—	9°

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